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Markus Makoschitz, AIT Austrian Institute of Technology, AT; Michael Hartmann, Schneider Electric, AT; Hans Ertl, Vienna University of Technology, AT

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Tom Ribarich, Stephen Oliver, Navitas Semiconductor, USA

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Klaus Sobe, Fabio Brucchi, Infineon Technologies Austria, AT

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**Technological Possibilities of New Silicon-Carbide Mosfets in Power-Inverter for the Inductive Energy Transfer**

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**Five-Level Cascaded Flying-Capacitor Converter**

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Akihiro Osawa, Keiichi Higuchi, Akio Kitamura, Daisuke Inoue, Yoshikazu Takamiya, Souichi Yoshida, Hiromichi Gohara, Masahito Otsuki, Fuji Electric, J

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Rajagopalan Jagannathan, Marco Atzeri, Hans-Peter Hoenes, ON Semiconductor, D

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Zarina Davletzhanova, Olayiwola Alatise, Jose Ortiz Gonzalez, Sylvia Konaklieva, Roozbeh Bonyadi, University of Warwick, GB

**High Efficiency and Ruggedness Intelligent IGBT Technology for EV/HEV**

Vittorio Crisafulli, ON Semiconductor, D

**Highly Integrated Power Unit Based on Double Sided Cooling IGBT Module**

Yun Li, Shiwu Zhu; Yaing Ma, Yangang Wang, Mingliang Jiao, Chundong Wu, Zhenlong Zhao, Jun Yu, Dynex Semiconductor, GB

**Efficiency Increasing by a Variable DC Link Voltage in Combination with a Bang-Bang Controlled Inverter for an Automotive Application**

Magnus Böh, Andreas Lohner, Noureddine El Amrani, TH Köln, D

**Magnetic Leakage Azimuth Pattern of a 7 Kw Wireless Electric Charging System in Different Environments**

Leandro Percebon, Daniel Kuerschner, Qualcomm CDMA Technologies, D

**Innovations for IGBT Based Power Modules in HEV Drivetrain Applications**

Thomas Geinzer, Martin Gleich, Alexander Schwarz, Infineon Technologies, D

**Estimation of the Losses in Si and SiC Power Modules for Automotive Applications**

Dounia Oustad, Menouar Ameziani, Dominique Lhotellier, VEDECOM, F; Stéphane Lefebvre, Meckael Petit, ENS Cachan, F

**DC/DC-Converter with Optimised Power Density for Integration of Multifunctional Fuel Cell Systems in Modern Aircraft Application**

Mathias Warncke, Klaus F. Hoffmann, Sebastian Fahlbusch, Helmut Schmidt University- University of the Federal Armed Forces Hamburg, D

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Martin Stempfle, Yuying Han, Julian Wöfle, Nathan Tröster, Jörg Roth-Stielow, University of Stuttgart, D

**Finite Control Set Model Predictive Control of a PMSM Fed by a Multilevel Inverter**

Cristian Vargas, Simon Feuersänger, Mario Pacas, University of Siegen, D

**Current Control Delay Reduction for FPGA-Based Servodrive**

Lev Rassudov, Balkovoi Aleksandr, Moscow Power Engineering Institute, RU

**Optimal Compensation Capacitors Maximizing Coreless Inductive Power Transfer**

Yohan Wanderoild, Romain Grezard, Gael Pillonnet, Dominique Bergogne, Adrien Morel, CEA-Léti, F; Hubert Razik, Laboratoire Ampère, F

**Switching Loss Minimization Using Two-Configuration Predictive Control for a Thermo-Hydraulic Linear PMSG**

Daniel Bernet, Karlsruhe Institute of Technologie (KIT), D; Robert Seifert, Technical University of Dresden, D

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Mitja Koprivsek, ETI, SI

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Toshihiro Shima, Koji Kato, Keisuke Nakano, Yoichi Ito, Sanken Electric, J; Hitoshi Haga, Nagaoka University of Technology, J; Kenji Arimatsu, Katsuhiko Matsuda, Tohoku Electric Power, J

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Swen Bosch, Jochen Staiger, Heinrich Steinhart, HTW Aalen, D

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Jan Leuchter, Quang Huy Dong, University of Defence, CZ

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Tsveti Hranov, Nikolay Hinov, Technical University of Sofia, BG

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Panagiotis Mantzanas, Thomas Duerbaum, Friedrich-Alexander-University Erlangen, D

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Carmelo Giuseppe Viccica, Marcello Palano, Natale Porto, STMicroelectronics, I

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Epameinondas Kontos, Haris Papadakis, Michalis Poikilidis, Pavol Bauer, Delft University of Technology, NL

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Mohamed Abdelrahman, Ralph Kennel, Technical University of Munich, D

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Michael Martinek, Jürgen Pröll, Oxana Kleinöder, e-laborate Innovations, D; Günther Greiner, Friedrich-Alexander-University Erlangen-Nürnberg, D

**Power-Hardware-In-Loop Setup for Power Electronics Tests**

Giovanni De Carne, Marius Langwasser, Xiang Gao, Giampaolo Buticchi, Marco Liserre, Christian-Albrechts-University, D

**Ensuring Fast Turn-Around Times for A Programmable Digital Power Controller**

Markus Schnell, Jörg Oehmen, Infineon Technologies, D

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Marco Schilling, Tobias Reimann, Technical University Ilmenau, D; Ulf Schwalbe, ISLE Steuerungstechnik und Leistungselektronik, D

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Carsten Kuring, Technical University Berlin, D; Julian Dobusch, Thomas Dürbaum, Friedrich-Alexander-University Erlangen, D

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Selimcan Deda, Roland Greul, Guenter Prochart, AVL LIST, AT

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Robert Lassartesses, Renault, F

**The Smart Future of Power Electronics and its Applications**

Hans Krattenmacher, SEW-Eurodrive, D

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Ionel Dan Jitaru, Rompower, USA